

RADITEK

VCO Application Note

Footprint : see Data sheet

Plated Through Holes (PTH)

A ground area should be provided immediately under the VCO and connected to the bottom side of the PCB via PTH.

Ideally use PTH corresponding to each ground half hole on the perimeter of the VCO.

PTH hole diameter to be equal to the board thickness to minimize ground reactance

Solder Reflow Max Temperature 220°C

Our VCO use Sn95 Solder with a melting temperature of 235°C

Temperature up and down ramp not to exceed 2 °C/second

Soak 155°C, 60-90 seconds

Recommended time above 183 °C 60 seconds

Solder Paste SN63 or similar